

# PATENT ASSIGNMENT

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Tong-Yu Chen	08/03/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	UNITED MICROELECTRONICS CORP.
<b>Street Address:</b>	No.3, Li-Hsin Road 2, Science-Based Industrial Park
<b>City:</b>	Hsin-Chu City
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13206523
<b>CORRESPONDENCE DATA</b>	
Fax Number: (703)997-4517 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 3027291562 Email: Patent.admin.uspto.cr@naipo.com Correspondent Name: WINSTON HSU Address Line 1: P.O.BOX 506 Address Line 4: Merrifield, VIRGINIA 22116	
<b>ATTORNEY DOCKET NUMBER:</b>	NAUP1329USA
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Total Attachments: 2 source=1178739#page1.tif source=1178739#page2.tif	

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**PATENT**  
**REEL: 026724 FRAME: 0001**

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Tong-Yu Chen Nationality: TW

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"Semiconductor Structure and Manufacturing Method Thereof"

Which is found in :

- (a) + U.S. patent application executed on even date  
(b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_  
(c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_  
(d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_  
(e) \_\_\_\_\_ International application no. \_\_\_\_\_

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this AUG 03 2011 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Tong-Yu Chen

Signature of INVENTOR

陳東裕, Tong-Yu, Chen